

AMENDMENTS TO CLAIMS:

Please amend the claims as follows:

1. (Previously presented) A lead frame comprising:
a lead frame body comprising a sheet-shaped body made of metal;
a groove portion for forming a lead which is formed by a predetermined depth in a lead forming region on a surface of the lead frame body; and
a lead having a portion which protrudes from the groove portion laterally onto the surface of the lead frame body so as to be in contact with said surface, the lead completely filling the groove portion and being made of material different from material of the lead frame body,
the lead including: a first conductor layer formed in the groove portion;
a second conductor layer formed on the first conductor layer; and
a third conductor layer formed on the second conductor layer, wherein
the first conductor layer is assembled to an assembling member, and
the third conductor layer is assembled to a die pad of a semiconductor chip,
wherein the lead includes a barrier layer for suppressing a reaction between the lead frame body and the first conductor layer, the barrier layer being provided on a part of the groove portion so as to be in contact with the lead frame body in the groove portion, and
wherein the barrier layer is made of any one of nickel, titanium or tungsten.
2. (Cancelled)
3. (Currently amended) A lead frame according to claim 1, wherein the first conductor layer covers an entire inner wall of the groove portion ~~through a buffer layer.~~

4. (Previously presented) A lead frame according to claim 1, wherein an interface of the first and the second conductor layer is located above the surface of the lead frame body.

5. (Previously presented) A lead frame according to claim 1, wherein the barrier layer is made of nickel.

6. (Previously presented) A lead frame according to claim 1, wherein the first conductor layer is made of metal capable of forming an alloy together with solder.

7. (Previously presented) A lead frame according to claim 1, wherein the film thickness of the first and the second conductor layer is 0.5 to 2 μm .

8. (Previously presented) A lead frame according to claim 1, wherein the first conductor layer comprises a gold layer.

9. (Previously presented) A lead frame according to claim 1, wherein the third conductor layer comprises a gold layer.

10. (Previously presented) A lead frame according to claim 1, wherein the second conductor layer comprises a metallic layer, the primary component of which is nickel.

11-33. (Canceled)